



SIRUS T2

Tabletop Reactive Ion Etcher (RIE)

The Sirius T2 RIE is a basic plasma etching system designed to etch dielectrics and other films that require fluorine-based chemistries. The small footprint and robust design make it ideal for the lab environment.

Applications

Processes have been developed for etching silicon, silicon dioxide, silicon nitride, quartz, polyimide, tantalum, tungsten, titanium tungsten and other materials that require profile control, high selectivity and good uniformity. For a more detailed discussion of applications and processes, please visit www.triontech.com.

Standard Features

- Sirius T2 reactor with 200mm bottom electrode
- System controller (includes Pentium™ based computer and touch screen interface)
- Two mass flow controllers
- Automatic tuning with 13.56 MHz 600 watt RF generator
- Emergency Off system
- Automatic pressure control package (butterfly valve with capacitance manometer for pressure measurement)
- 12 month limited warranty

Optional Features

- Recirculating temperature controller
- Up to two additional mass flow controllers

Pumps

- Optional 245 l/s turbo pump
- 23.3 cfm rotary vane pump with oil filtration, demister, and Fomblin oil
- The Sirius T2 system requires a roughing pump and either a chiller or cooling water with greater than 4 M ohm resistivity.





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